



Potting & Encapsulation Materials

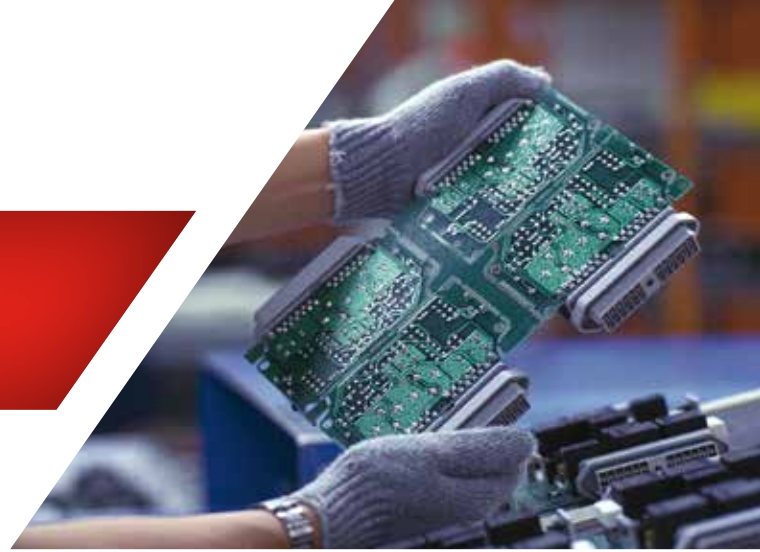
CATALOG

LORD
AskUsHow™



**LORD Partners with
Customers to Leverage
Expertise in Multiple
Chemistries and Diverse
Applications to Develop
Customized Solutions.**

Design Compromise Not An Option?

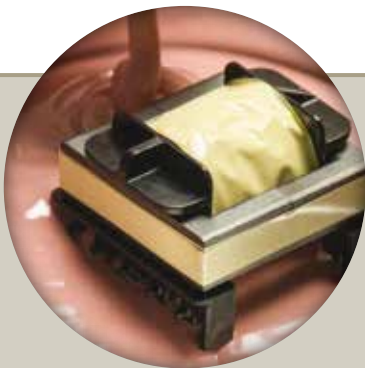


At LORD, we have been developing custom potting and encapsulant solutions for more than 50 years. Whether utilizing epoxy, silicone or urethane polymer systems, we continue to deliver results for demanding applications in a wide variety of industries including automotive, energy, medical, aerospace, telecommunications and industrial electronics based on our customers' design and specification needs.

Our products offer diverse encapsulant application options including use in ignition coils, engine control

modules, transmission control modules, sensors, power supplies, transformers and other critical electronic equipment.

If you need help choosing one of our standard potting and encapsulant products or if you need a custom material to meet your needs, let us help you determine an appropriate solution for your application ... Ask Us How.



SILICONES

Silicones are one of the most versatile chemistries and offer inherent flexibility spanning over a wide temperature range (-75°C to +200°C). Silicone products are widely known to protect fragile electronic components and modules where flame and high temperature resistance and permanent flexibility are top priorities. We offer platinum-cured, soft silicone and condensation-cured silicone rubbers, either unfilled clear or filled.



EPOXIES

Epoxy provides strength, versatility, durability, adhesion, chemical resistance and high temperature tolerance in adhesive, potting and encapsulant applications. These products can be formulated to fit a variety of applications and requirements thanks to the wide availability of raw materials. We offer a wide range of epoxy products from extremely flexible to highly-rigid casting materials, either filled or unfilled, that are thermally and/or electrically conductive and flame retardant.



URETHANES

Urethanes are considered to be a great alternative to silicones when high temperature resistance is not required. For electronic packaging, urethanes are known to work best in low-temperature applications. They protect stress-sensitive electronic devices and act as a barrier against water. We offer low viscosity urethane products ranging from soft gels to semi-rigid casting materials that are designed to fit various potting application needs.

	Chemistry	Thermally Conductive	Components		Can be used with multiple hardeners	UL Rating	Appearance
			1k	2k			
CoolTherm™ SC-6702	Silicone	x		x		UL 94 V-0	Red
CoolTherm SC- 6703	Silicone	x		x		UL 94 V-0	Light Gray
CoolTherm SC-6703 LV	Silicone	x		x		UL 94 V-0	Light Gray
CoolTherm SC-6708/6731	Silicone	x		x			White
CoolTherm SC-6709	Silicone	x		x	x		White
CoolTherm SC-6710/6731	Silicone	x		x			Red
CoolTherm SC-6711	Silicone	x		x	x		White
CoolTherm SC-6725	Silicone	x		x			Red
CoolTherm SC-6726	Silicone	x		x			Red
CoolTherm SC-324	Silicone	x		x			Light Pink
CoolTherm SC-252	Silicone	x		x			Gray
CoolTherm SC-104	Silicone	x		x		UL 94 V-0	Gray
CoolTherm SC-303	Silicone	x		x		UL 94 V-0, UL RTI 200°C	Gray
CoolTherm SC-305	Silicone	x		x		UL 94 V-0, UL RTI 170°C	Gray
CoolTherm SC-309	Silicone	x		x		UL 94 V-0, UL RTI 180°C	Gray
CoolTherm SC-320	Silicone	x		x		UL 94 V-0, UL RTI 180°C	Light Pink
Thermoset™ SC-318S	Silicone		x				Green
Circalok™ 6712/6730	Silicone			x			White
Circalok 6715/6730	Silicone			x			White
Circalok 6716/6733	Silicone			x			Black

Viscosity (cps @ 25°C)	Mix Ratio by Weight	Cure Schedule	Hardness	Tensile Shear Strength (psi)	Thermal Conductivity (W/mK)	Description
30,000	1:1	16-24 hr @ 85°C	65 Shore A	600	0.7	High density, thermally conductive primerless silicone for encapsulating sensitive electronic modules
8,000	1:1	4 hr @ 65°C	60 Shore A	200	0.8	Two-component, thermally conductive silicone for encapsulating densely packed power units
5,000	1:1	4 hr @ 65°C	40 Shore A	30	0.8	Two-component, thermally conductive, low viscosity silicone for encapsulating densely packed power units
30,000	100:0.5	12-16 hr @ 25°C; or 4 hr @ 65°C	60 Shore A	350	0.8	Thermally conductive silicone with good electrical properties
30,000	Hardener Dependent	Hardener Dependent	45-60 Shore A	310	1.0	Two-component, thermally conductive silicone with outstanding electrical properties
20,000	100:0.5	12-16 hr @ 25°C	65 Shore A	800	1.0	Two-component, low viscosity, thermally conductive RTV silicone for applications requiring low stress, rapid heat transfer, high temperature and repairability
30,000	Hardener Dependent	Hardener Dependent	60 Shore A	800	1.0	Two-component, thermally conductive silicone with outstanding electrical properties
15,000	1:1	4 hr @ 85°C	45 Shore A	550	1.16	High density, thermally conductive, primerless silicone
56,000	1:1	4 hr @ 85°C	70 Shore A	600	0.8	High density, thermally conductive, primerless silicone
23,000	1:1	24 hr @ 25°C; or 60 min @ 125°C	50 Shore A	119	4.0	Two-component, high thermally conductive silicone for electrical/electronic encapsulating applications
10,000	1:1	24 hr @ 25°C; or 30 min @ 120°C	60 Shore A	145	2.5	Two-component, medium thermally conductive silicone which can be cured at relatively low temperature
7,000	1:1	24 hr @ 25°C; or 10-15 min @ 100°C	65 Shore A	480	0.8	Two-component, thermally conductive silicone
6,000	1:1	24 hr @ 25°C; or 10-15 min @ 100°C	45 Shore A	170	0.9	Two-component, thermally conductive silicone for encapsulating applications requiring high heat dissipation
4,000	1:1	24 hr @ 25°C; or 10 min @ 100°C	60 Shore A	215	0.7	Two-component, thermally conductive silicone for the protection of electrical/electronic applications where heat dissipation is critical
3,600	1:1	24 hr @ 25°C; or 10 min @ 120°C	45 Shore A	50	1.0	Two-component, thermally conductive silicone for the protection of electrical/electronic applications where heat dissipation is critical
22,000	1:1	24 hr @ 25°C; or 60 min @ 125°C	60 Shore A	313	3.2	Two-component, thermally conductive silicone for the protection of electrical/electronic applications where heat dissipation is critical
45,000		45-75 min @ 125°C; or 30-60 min @ 150°C	40 Shore OO	200		One-component, rapid cure silicone designed for use as an encapsulant or coating to protect electronic devices
7,250	10:1	12 hr @ 25°C; or 2 hr @ 65°C	35 Shore A	340		Two-component, solvent-free silicone for potting and encapsulating densely packed components and making flexible molds
14,000	10:1	24 hr @ 25°C; or 2-4 hr @ 65°C	35 Shore A	250		Two-component, solvent-free silicone for potting and encapsulating densely packed components and making flexible molds
10,000	100:2.5	12-16 hr @ 25°C	45 Shore A	140		Solvent-free silicone for potting and encapsulating low- and high-voltage electrical assemblies

	Chemistry	Thermally Conductive	Components		Can be used with multiple hardeners	UL Rating	Appearance
			1k	2k			
Circalok 6717/6731	Silicone			x			Red
Circalok 6735	Silicone			x			Clear
Circalok 6744	Silicone			x		UL 94 V-0	Gray
Circalok 6750	Silicone			x			Gray
Thermoset SC-300M	Silicone			x			Clear
Thermoset SC-316	Silicone			x			White
Thermoset SC-319	Silicone			x			Black
Circalok 6756	Adhesion Promoter - Silicone						Clear or Red
Thermoset P-1291	Adhesion Promoter - Silicone						Clear or Red
Thermoset P-1292	Adhesion Promoter - Silicone						Blue
CoolTherm EP-3500	Epoxy	x		x			Dark Gray
CoolTherm EP-6006 HS/ EP-6011 H	Epoxy	x		x		UL 94 V-0	Black
CoolTherm EP-6007/EP-6010 H	Epoxy	x		x		UL 94 V-0	Black
CoolTherm EP-6035	Epoxy	x		x		UL 94 V-0	Black
CoolTherm EP-6037/EP-6252	Epoxy	x		x			Black or Green
CoolTherm EP-340	Epoxy	x		x	x	UL 94 HB (only with Thermoset Hardener No. 70)	Black
CoolTherm EP-301 AD	Epoxy	x		x	x		Black or White
CoolTherm EP-343	Epoxy	x		x			Black
CoolTherm EP-6150	Epoxy	x	x				White
Thermoset EP-870	Epoxy		x				Black
Thermoset EP-937	Epoxy		x				Black
Thermoset ES-21	Epoxy		x				Black
Thermoset ES-95	Epoxy		x				Black

Viscosity (cps @ 25°C)	Mix Ratio by Weight	Cure Schedule	Hardness	Tensile Shear Strength (psi)	Thermal Conductivity (W/mK)	Description
17,000	100:5	8-12 hr @ 25°C	60 Shore A	700		Two-component, condensation curing, solvent-free silicone RTV for potting, encapsulating or coating applications
3,500	10:1	4 hr @ 65°C	40 Shore A	750		Clear, low viscosity, two-component silicone that produces a clear, flexible elastomer that adheres to most substrates without a primer
2,700	1:1	2 hr @ 25°C; or 45 min @ 65°C	55 Shore A	400		Low viscosity, flame retardant, room temperature curing silicone
6,000	1:1	24 hr @ 25°C; or 2 hr @ 65°C	45 Shore A	300		Low viscosity, microballoon-filled, room temperature curing silicone
200	1:1	24 hr @ 25°C	Gel			Electronic-grade silicone gel encapsulant
200	1:1	1 hr @ 25°C	Gel			Electronic-grade silicone gel encapsulant
1,000	1:1	2 hr @ 25°C	70 Shore OO			Two-component, room temperature curing silicone encapsulant
1		60-90 min @ 25°C				Primer for bonding RTV silicones to metal and glass
5		30-60 min @ 25°C				Electronic-grade primer for bonding tin-catalyzed RTV silicone to most metals and glass
5		30-60 min @ 25°C				Electronic-grade primer for bonding platinum-catalyzed RTV silicone to most metals and glass
11,700 @ 60°C	1:1	Staged Cure: 2 hr each @ 120°C, 150°C, 180°C & 210°C	90 Shore D		3.5	Two-component, electrically insulating epoxy encapsulant with very high thermal conductivity, low thermal expansion and high-temperature stability
22,500	100:17.5	24 hr @ 25°C; or 2 hr @ 65°C	90 Shore D	9,800	1.1	Thermally conductive, low shrinkage, two-component epoxy
15,000	100:5.5	12-16 hr @ 25°C	85 Shore D	8,400	0.6	Thermally conductive adhesive and potting compound
12,000	1:1	24 hr @ 25°C; or 2 hr @ 65°C	75 Shore D	5,000	1.0	Low viscosity, flame retardant, room temperature curing epoxy
100,000	100:7.1	24 hr @ 25°C; or 2 hr @ 65°C	92 Shore D	8,700	1.1	Two-component epoxy for the semiconductor industry
300,000	Hardener Dependent	Hardener Dependent	90-95 Shore D	6,300-9,400	Hardener Dependent	Filled, thermally conductive epoxy for use with various hardeners
10,000	Hardener Dependent	Hardener Dependent	85-90 Shore D	9,890	1.2	Thermally conductive casting epoxy
55	100:3.9	2 hr @ 65°C followed by 4 hr @ 135°C	90 Shore D	8,300	1.1	Two-component, thermally conductive, dielectric epoxy coating
145,000		30 min @ 121°C; or 10 min @ 177°C	90 Shore D		0.6	One-component, thixotropic epoxy for assembling electronic components and devices
Thixotropic Paste		45-60 min @ 120°C; or 10-25 min @ 150°C	88 Shore D	8,200		One-component, fast curing epoxy
47,900		18-28 min @ 120°C; or 6-12 min @ 150°C	88-94 Shore D			One-component, fast curing epoxy
35,000		60 min @ 125°C	88 Shore D	7,100		One-component, fast curing epoxy containing a fluorescent dye for detection under UV light
75,000		30-60 min @ 125°C	88 Shore D	5,900		One-component, fast curing epoxy that provides excellent thermal shock resistance

	Chemistry	Thermally Conductive	Components		Can be used with multiple hardeners	UL Rating	Appearance
			1k	2k			
Thermoset LS 213-9	Epoxy		x				Amber
CoolTherm EP-6008	Epoxy	x		x	x		Black or White
CoolTherm EP-6009	Epoxy	x		x		UL 94 V-0	Black
Circalok 6013	Epoxy			x			Orange
Circalok 6015	Epoxy			x			Orange
Circalok 6021	Epoxy			x			Gray
Circalok 6022	Epoxy			x			Yellow
CoolTherm EP-6028/6029	Epoxy	x		x			Blue
Circalok 6031	Epoxy			x			Beige
Circalok 6055	Epoxy			x			Black
Thermoset 300	Epoxy			x	x		Black
Thermoset 600	Epoxy			x	x		Amber
Thermoset DC-80	Epoxy			x			Gray
Thermoset DC-946	Epoxy			x			Black
Thermoset E-105 Clear	Epoxy			x	x		Clear
CoolTherm EP-636	Epoxy	x		x			Gray
Thermoset EP-20	Epoxy			x	x		Black
Thermoset EP-809	Epoxy			x			Gray
Thermoset EP-830	Epoxy			x			Tan
Thermoset EP-866	Epoxy			x			Gray
Thermoset ES-40	Epoxy			x	x		White
Thermoset ES-73	Epoxy			x			Green
Thermoset ES-100	Epoxy			x			Black

Viscosity (cps @ 25°C)	Mix Ratio by Weight	Cure Schedule	Hardness	Tensile Shear Strength (psi)	Thermal Conductivity (W/mK)	Description
2,800		5 hr @ 104°C; or 2 hr @ 120°C	85 Shore D	6,000		One-component, impregnating epoxy
8,000	Hardener Dependent	12 hr @ 25°C; or 2 hr @ 65°C	85 Shore D	7,200	0.3	Filled, low viscosity, general purpose potting and encapsulating epoxy
2,600	10:1	2-4 hr @ 65°C	90 Shore D	7,000	0.7	Two-component epoxy
17,500	100:2.2	2 hr @ 65°C	90 Shore D	8,100		High density, fast curing, sound deadening, radiation-opaque, high lead-filled epoxy
17,000	100:2.9	24 hr @ 25°C	90 Shore D	8,100		High density, fast curing, sound deadening, radiation-opaque, lead-filled epoxy
200,000	100:85	24 hr @ 25°C; or 2 hr @ 65°C	85 Shore D	7,400		Two-component, room temperature curing epoxy with long working life, good peel strength and adhesion to metals, plastics, fiberglass and wood
50,000	100:87	24 hr @ 25°C	67 Shore D	>3,000		Two-component, room temperature curing epoxy with good peel strength and adhesion to metals, plastics, fiberglass and wood
15,000	1:1	3-4 hr @ 100°C	90 Shore D	7,200	0.45	Filled, two-component epoxy for potting high voltage transformers, especially for high temperature devices
13,000	3:1	1 hr @ 120°C plus 4 hr @ 160°C; or 2 hr @ 85°C plus 12 hr @ 120°C	60 Shore D	2,000		Two-component epoxy with excellent electrical properties at high temperatures
4,000	1:1	24 hr @ 25°C; or 2 hr @ 60°C	77 Shore D	3,000		Two-component, room temperature curing epoxy with long working life
68,000	Hardener Dependent	Hardener Dependent	65-95 Shore D	2,000 - 9,800		Filled, thermal shock resistant epoxy for use with various hardeners
13,5000	Hardener Dependent	Hardener Dependent	60-90 Shore D	2,300 - 10,900		Unfilled, moderate viscosity epoxy for use with various hardeners
Thixotropic Paste	1:1	24 hr @ 25°C; 5 min @ 121°C	82 Shore D	5,000		Epoxy used in varying mix ratios to provide optimum properties
12,000	1:1	2-3 hr @ 95°C	86 Shore D	5,700		Two-component, heat curing epoxy with excellent thermal shock resistance
600	Hardener Dependent	Hardener Dependent	65-92 Shore D	1,250 - 9,300		Clear, low viscosity, general purpose epoxy
50,000	100:1	16-24 hr @ 50-65°C followed by 2 hr each @ 95°C, 150°C & 205°C	95 Shore D	6,200	1.0	Ultra-high temperature resistant encapsulating epoxy
12,000	Hardener Dependent	Hardener Dependent	60-90 Shore D	2,300 - 11,200		Black, unfilled, moderate viscosity epoxy for use with various hardeners
2,800	100:32	12-16 hr @ 80-90°C; or 2 hr @ 90-95°C plus 2 hr @ 115-125°C	92 Shore D	11,500		Ignition coil impregnating encapsulating epoxy
4,000	100:28	3 hr @ 100°C plus 2 hr @ 150°C	97 Shore D	12,000		Coil impregnating, encapsulating epoxy for ignition coil applications
Thixotropic Paste	1:1	24 hr @ 25°C; or 5 min @ 121°C	82 Shore D	5,000		Epoxy used in varying mix ratios to provide optimum properties
12,000	Hardener Dependent	Hardener Dependent	60-90 Shore D	2,300 - 10,900		Unfilled, moderate viscosity epoxy for use with various hardeners
10,000	100:82	30 min @ 25°C	75 Shore D	3,000		Two-component, rapid curing epoxy used as an anchor bond adhesive for car batteries
1,200	1:1	3-4 hr @ 80°C	70 Shore OO	65		Two-component epoxy for encapsulating intricate electronic components in automotive, marine and heavy industrial applications

	Chemistry	Thermally Conductive	Components		Can be used with multiple hardeners	UL Rating	Appearance
			1k	2k			
Thermoset ES-115	Epoxy			x			Tan
Thermoset ES-121 LV2/EP-809	Epoxy			x			Black
Thermoset MP 110-10	Epoxy			x			Black
Thermoset Hardener No. 18	Epoxy			x			Amber
Thermoset Hardener No. 25	Epoxy			x			Amber
Thermoset Hardener No. 37	Epoxy			x			Amber
Thermoset Hardener No. 65	Epoxy			x			Tan
Thermoset Hardener No. 66	Epoxy			x			Amber
Thermoset Hardener No. 67	Epoxy			x			Clear
Thermoset Hardener No. 70	Epoxy			x			Tan
Thermoset Hardener No. 71	Epoxy			x			Light Amber
Thermoset Hardener No. 72	Epoxy			x			Black
LORD® AP-134	Adhesion Promoter - Epoxy or Urethane						Clear, Straw Yellow
CoolTherm UR-288	Urethane	x		x		UL 94-HB	Black
CoolTherm UR-388	Urethane	x		x		UL 94 V-0	Black
CoolTherm UR-388 Fast	Urethane	x		x		UL 94 V-0	Black
Circalok 6403	Urethane			x			Amber or Black
Circalok 6404	Urethane			x			Amber
Circalok 9154FR	Urethane			x			Amber
Thermoset UR-105	Urethane			x			Black
Thermoset UR-312	Urethane			x			Amber
Thermoset UR-322	Urethane			x			Amber
Thermoset UR-325	Urethane			x			Black

Viscosity (cps @ 25°C)	Mix Ratio by Weight	Cure Schedule	Hardness	Tensile Shear Strength (psi)	Thermal Conductivity (W/mK)	Description
85,000	1:1	2.5 hr @ 85°C plus 1.5 hr @ 125°C	90 Shore D	10,200		Two-component epoxy for high voltage, automotive ignition coils
4,500	100:29	2 hr @ 90°C followed by 2.5 hr @ 140°C	>90 Shore D			Two-component epoxy for high voltage, automotive ignition coils
75,000	1:1 by Volume	24 hr @ 25°C	45 Shore A	500		Unfilled epoxy with good thermal shock performance and excellent chemical resistance
50	100:14 (with 600 Resin)	24 hr @ 25°C (w/600 Resin)	88 Shore D (with 600 Resin)	11,200 (with 600 Resin)		Room temperature hardener
5,000	100:100 (with 600 Resin)	24 hr @ 25°C (w/600 Resin)	80 Shore D (with 600 Resin)	8,200 (with 600 Resin)		High surface gloss, fast setting, moisture insensitive hardener
40,000	100:54 (with 600 Resin)	24 hr @ 25°C; or 5 min @ 93°C (w/600 Resin)	84 Shore D (with 600 Resin)	7,500 (with 600 Resin)		Hardener that produces epoxies with improved flexibility and impact strength
50	100:40 (with 600 Resin)	24 hr @ 25°C (w/600 Resin)	85 Shore D (with 600 Resin)	9,000 (with 600 Resin)		High surface gloss, long working life, moisture insensitive hardener
10,000	100:50 (with 600 Resin)	24 hr @ 25°C (w/600 Resin)	85 Shore D (with 600 Resin)	7,600 (with 600 Resin)		General purpose hardener well-suited for a variety of applications
30	100:24 (with 600 Resin)	2 hr @ 100°C (w/600 Resin)	92 Shore D (with 600 Resin)	10,900 (with 600 Resin)		Long working life, heat curing hardener with high Tg
30	100:30 (with 600 Resin)	24 hr @ 25°C (w/600 Resin)	82 Shore D (with 600 Resin)	8,650 (with 600 Resin)		High impact strength hardener
125	100:100 (with 600 Resin)	24 hr @ 25°C (w/600 Resin)	60 Shore D (with 600 Resin)	2,300 (with 600 Resin)		Semi-rigid, low exotherm hardener
7,000	100:100 (with 300 Resin)	24 hr @ 25°C (w/300 Resin)	65 Shore D (with 300 Resin)	2,020 (with 300 Resin)		Filled, room temperature curing hardener with low exotherm and semi-rigid encapsulation
3.5		1-2 hr @ 25°C				Moisture-cure primer for epoxy or polyurethane
	100:20	24 hr @ 25°C or 6 hr @ 60°C	90 Shore A	1,204	0.4	Two-component, room temperature curing, flame retardant urethane potting compound
6,000	100:20	24 hr @ 25°C or 6 hr @ 60°C	90 Shore A	2,260	0.7	Two-component, flame retardant, semi-flexible urethane for encapsulating and casting applications
6,000	100:20	30 min @ 25°C	88 Shore A	2,260	0.7	Two-component, flame retardant, semi-flexible urethane for encapsulating and casting applications
900	22:10	30-45 min @ 25°C	80 Shore A	1,935		General purpose, encapsulating urethane for applications requiring a fast cure, mechanical shock resistant system
900	100:45	30-45 min @ 25°C; or 5-10 min @ 100°C	80 Shore A	1,935		General purpose, encapsulating urethane for applications requiring a fast cure, mechanical shock resistant system
4,000	1:2	16 hr @ 25°C; or 1 hr @ 75°C	90 Shore A	2,223		Two-component, solvent-free, unfilled, casting urethane for potting electrical cables, general marine sealing and caulking
1,500	100:9	24 hr @ 25°C; or 3 hr @ 75°C	25 Shore A	120		Two-component, room temperature curing urethane encapsulating compound
1,500	100:55 2:1 by volume	24 hr @ 25°C; or 2 hr @ 85°C	50 Shore OO	50		Microelectronic grade, clear, low modulus urethane encapsulating gel
750	100:107 1:1 by volume	30 min @ 25°C	12 Shore A	100		Two-component, room temperature curing urethane encapsulating compound
4,000	4:1	24 hr @ 25°C	65 Shore A	770		Two-component, room temperature curing, urethane encapsulating compound



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Values stated herein represent typical values as not all tests are run on each lot of material produced. For formalized product specifications or specific product end uses, contact the Customer Support Center.

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